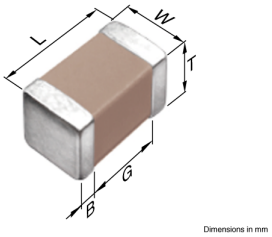
Creation Date : June 26, 2017 (GMT)

Multilayer Ceramic Chip Capacitors

CGA3E3X5R1H474K080AB

RoHS | REACH SVHC-Free | Halogen Free | Lead Free

TDK item description	CGA3E3X5R1H474KT****
Applications	Automotive Grade
Feature	General (Up to 50V) AEC-Q200
Series	CGA3(1608) [EIA 0603]
Status	Production



Size	
Length(L)	1.60mm ±0.10mm
Width(W)	0.80mm ±0.10mm
Thickness(T)	0.80mm ±0.10mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	0.30mm Min.
Recommended Land Pattern (PA)	0.70mm to 1.00mm(Flow Soldering) 0.60mm to 0.80mm(Reflow Soldering)
Recommended Land Pattern (PB)	0.80mm to 1.00mm(Flow Soldering) 0.60mm to 0.80mm(Reflow Soldering)
Recommended Land Pattern (PC)	0.60mm to 0.80mm(Flow Soldering) 0.60mm to 0.80mm(Reflow Soldering)

Electrical Characteristics	
Capacitance	470nF ±10%
Rated Voltage	50VDC
Temperature Characteristic	X5R(±15%)
Dissipation Factor (Max.)	5%
Insulation Resistance (Min.)	1063MΩ

Other	
Soldering Method	Wave (Flow) Reflow
AEC-Q200	Yes
Packing	Punched (Paper)Taping [180mm Reel]
Package Quantity	4000pcs

! Images are for reference only and show exemplary products.
! This PDF document was created based on the data listed on the TDK Corporation website.
! All specifications are subject to change without notice.

Copyright(c) TDK Corporation. All rights reserved.

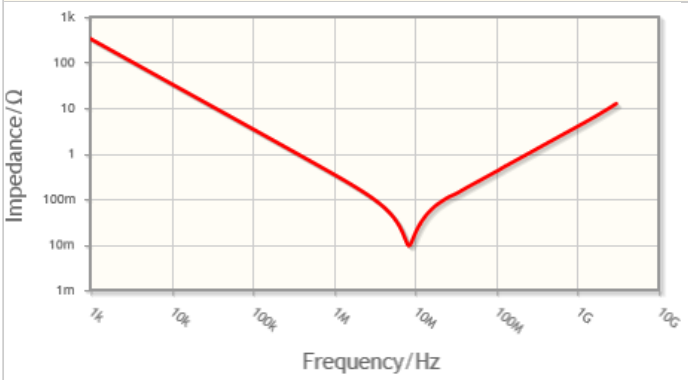
Multilayer Ceramic Chip Capacitors

CGA3E3X5R1H474K080AB

RoHS | REACH SVHC-Free | Halogen Free | Lead Free

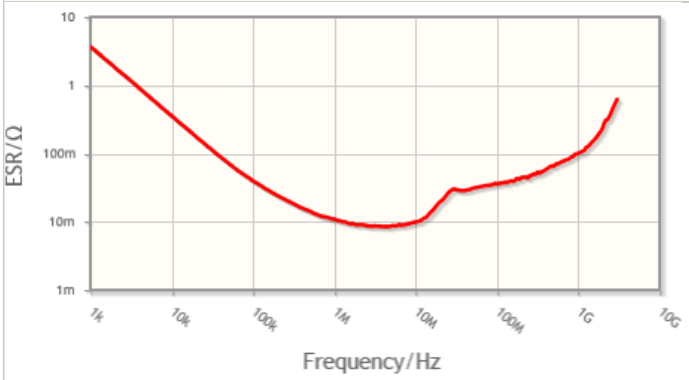
Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

Impedance



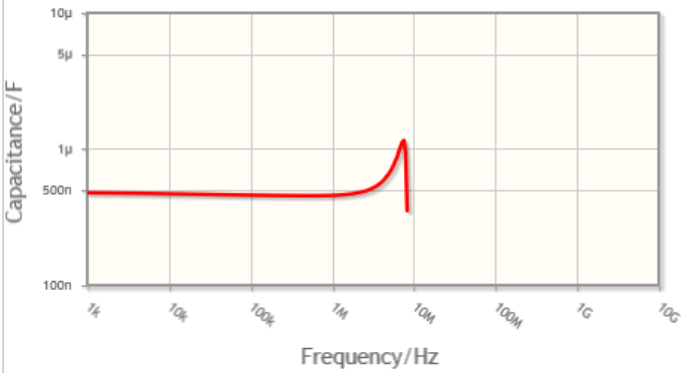
CGA3E3X5R1H474K080AB

ESR



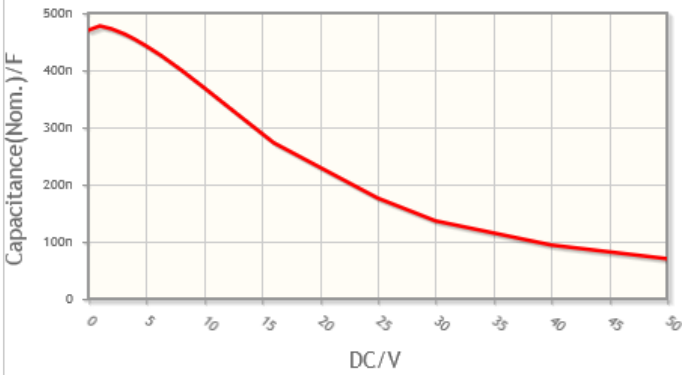
CGA3E3X5R1H474K080AB

Capacitance



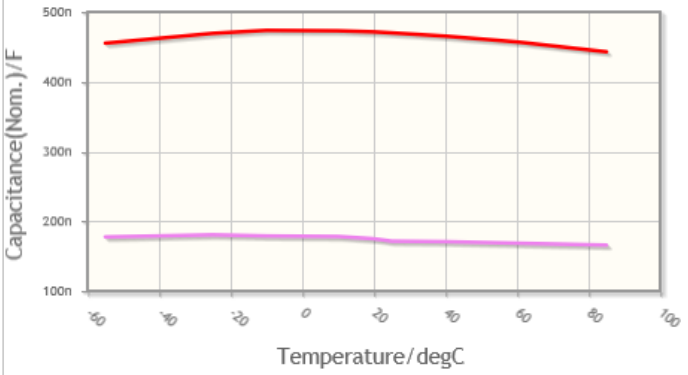
CGA3E3X5R1H474K080AB

DC Bias Characteristic



CGA3E3X5R1H474K080AB

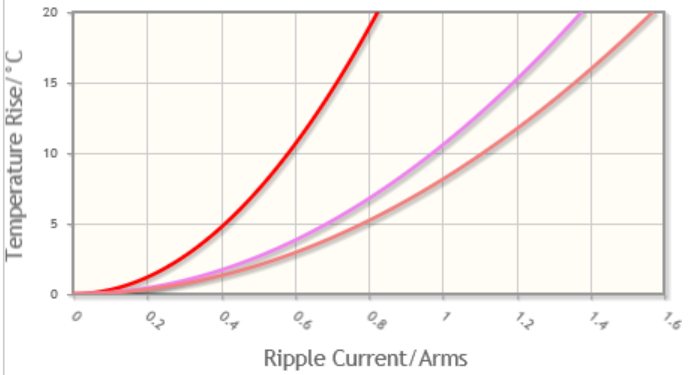
Temperature Characteristic



CGA3E3X5R1H474K080AB(No Bias)

CGA3E3X5R1H474K080AB(DC Bias = 25V)

Ripple Temperature Rising



CGA3E3X5R1H474K080AB(100kHz) CGA3E3X5R1H474K080AB(500kHz) CGA3E3X5R1H474K080AB(1MHz)

! Images are for reference only and show exemplary products.
! This PDF document was created based on the data listed on the TDK Corporation website.
! All specifications are subject to change without notice.

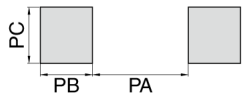
Copyright(c) TDK Corporation. All rights reserved.

Multilayer Ceramic Chip Capacitors

CGA3E3X5R1H474K080AB

Associated Images

Land Pattern (Terminal Connection)



! Images are for reference only and show exemplary products.
! This PDF document was created based on the data listed on the TDK Corporation website.
! All specifications are subject to change without notice.

Copyright(c) TDK Corporation. All rights reserved.